

**COAXIAL VIA STRUCTURE FOR OPTIMIZING SIGNAL TRANSMISSION
IN MULTIPLE LAYER ELECTRONIC DEVICE CARRIERS**

ABSTRACT

A coaxial via structure adapted to transmit high speed
5 signals or high intensity current through conductive layers of an
electronic device carrier is provided. The coaxial via structure
comprises a central conductive track and an external conductive
track separated by a dielectric material and is positioned in a
core of the electronic device carrier or in the full thickness of
10 the electronic device. The coaxial via structure can be combined
with a stacked via structure so as allow efficient transmission
of high speed signals across the electronic device carrier when a
manufacturing process limits the creation of a full coaxial via
structure across the entire electronic device carrier.